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Heat Sinkable Package

Abstract of the Disclosure

A heat sinkable package that includes a power device package including an active side and a non-active side is disclosed. The non-active side includes a heat sinkable surface positioned adjacent to a product case. Another embodiment of the invention is directed to a method for manufacturing a heat sinkable package. The method comprises the steps of placing at least one flip chip over a flexible circuit within a mold tool; compensating for height variances of the flip chips; and positioning an input/output on an active side of the power device package opposite a non-active side of the power device package.